

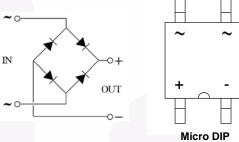
April 2012

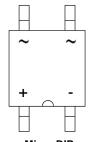
# MDB10SS

# 1A, MicroDIP, Single-Phase Bridge Rectifiers

## **Features**

- Low Package Profile: 1.45 mm (max)
- Requires Only 35 mm<sup>2</sup> of Board Space
- High Surge Current Capability: 30A (max)
- Glass Passivated Junction Rectifiers
- Smaller Plastic Body vs MDB10S
- Green Compound
- UL Certification: E352360





# **Absolute Maximum Ratings** $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Value	
$V_{RRM}$	Maximum Repetitive Peak Reverse Voltage	1000	V
V <sub>RMS</sub>	Maximum RMS Voltage	700	V
$V_{DC}$	Maximum DC Blocking Voltage	1000	V
I <sub>F(AV)</sub>	Average Rectified Forward Current *	1.0	Α
I <sub>FSM</sub>	Peak Forward Surge Current **	30	Α
I <sup>2</sup> t	I <sup>2</sup> t Rating for fusing (t<8.3ms)	3.735	A <sup>2</sup> S
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

<sup>\* 60</sup>Hz sine wave, R-load,  $T_A = 25$ °C on FR-4 PCB.

## Thermal Characteristics\*

Symbol	Parameter	Тур.	Units
$R_{ hetaJA}$	Thermal Resistance, Junction-Ambient - Measurement with Dual Dice - Measurement with Single Die	250 150	°C/W
ΨJL	Thermal Characterization, Junction to Lead - Measured at Anode pin - Measured at Cathode pin	57 15	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB with board size = 76.2mm x 114.3mm (JESD51-3 standards)

# **Electrical Characteristics** T<sub>A</sub> = 25°C unless otherwise specified

Symbol	Parameter	Test condition	Value	Units
V <sub>F</sub>	Maximum Forward Voltage	I <sub>F</sub> = 1A, Pulse measurement, Per diode	1.1	V
I <sub>R</sub>	Maximum Reverse Current	@ V <sub>RRM</sub> , Pulse measurement, Per diode	10	μΑ
CJ	Typical Junction Capacitance	$V_R = 4V, f = 1MHz$	10	pF

<sup>\*\* 60</sup>Hz sine wave, Non-repetitive 1 cycle peak value,  $T_J = 25$ °C.

# **Typical Performance Characteristics**

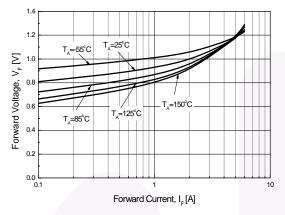


Figure 1. Forward Voltage vs Forward Current (Per diode)

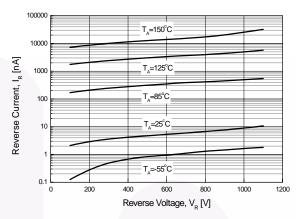


Figure 2. Reverse Current vs Reverse Voltage (Per diode)

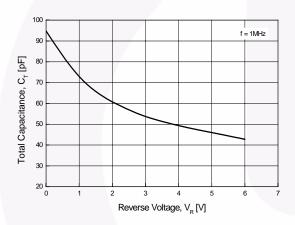
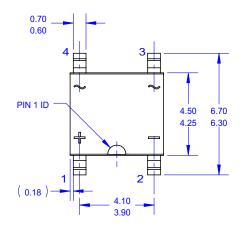
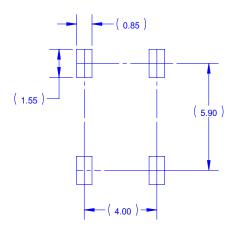


Figure 3. Total Capacitance

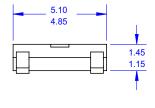
# **Physical Dimensions**



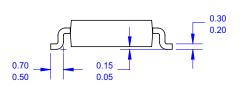


**TOP VIEW** 

LAND PATTERN RECOMMENDATION



SIDE VIEW



**END VIEW** 

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  B. ALL DIMENSIONS ARE IN MILLIMETERS.

  C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

  G. DRAWING FILE NAME: MKT-TDI04BREV1.

**Dimensions in Millimeters** 





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